

Product Change Notification - KSRA-10KDPB147

Date: 27 Sep 2017

Product Category: Capacitive Touch Sensors; Digital Potentiometers; Battery Management and Fuel Gauges - Battery Chargers; 8-bit PIC Microcontrollers

Notification subject: CCB 2909 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products for 160K wafer technology available in 20L QFN package at NSEB assembly site

Notification text: **PCN Status:**
Final notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CP.N.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products for 160K wafer technology available in 20L QFN package at NSEB assembly site

Pre Change:

Using gold (Au) bond wire, 8200T and 8600 die attach and G770HCD and G700LTD mold compound material.

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach and G700LTD mold compound material.

Pre and Post Change Summary:

	Pre Change		Post Change
Assembly Site	NSEB Assembly Site		NSEB Assembly Site
Wire material	Au Wire		CuPdAu Wire
Die attach material	8200T	8600	8600
Molding compound material	G770HCD	G700LTD	G700LTD
Lead frame material	EFTEC-64T		EFTEC-64T

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability and qualify CuPdAu bond wire at NSEB assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

October 27, 2017 (1743)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts

Time Table Summary:

Workweek	April 2017						-->	September 2017					October 2017				
	13	14	15	16	17	18		35	36	37	38	39	40	41	42	43	44
Initial PCN Issue Date					X												
Qual Report Availability											X						
Final PCN Issue Date											X						
Estimated Implementation Date																X	

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report

Revision History:

April 24, 2017: Issued initial notification.

September 27, 2017: Issued final notification. Attached the Qualification Report. Revised the affected parts list. Provided estimated first ship date on October 27, 2017.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

- [PCN_KSRA-10KDPB147_Affected CPN.pdf](#)
- [PCN_KSRA-10KDPB147_Qual Report.pdf](#)
- [PCN_KSRA-10KDPB147_Affected CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PCN_KSRA-10KDPB147
CATALOG_PART_NBR
AR1010-I/ML
AR1010T-I/ML
AR1011-I/ML
AR1011T-I/ML
AR1020-I/ML
AR1020T-I/ML
AR1021-I/ML
AR1021T-I/ML
MCP4331-103E/ML
MCP4331-104E/ML
MCP4331-502E/ML
MCP4331-503E/ML
MCP4331T-103E/ML
MCP4331T-104E/ML
MCP4331T-502E/ML
MCP4331T-503E/ML
MCP4341-103E/ML
MCP4341-104E/ML
MCP4341-502E/ML
MCP4341-503E/ML
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MCP4361-503E/ML
MCP4361T-103E/ML
MCP4361T-104E/ML
MCP4361T-502E/ML
MCP4361T-503E/ML
MCP4431-103E/ML
MCP4431-104E/ML
MCP4431-502E/ML

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Affected Catalog Part Numbers (CPN)

PCN_KSRA-10KDPB147
CATALOG_PART_NBR
MCP4431-503E/ML
MCP4431T-103E/ML
MCP4431T-104E/ML
MCP4431T-502E/ML
MCP4431T-503E/ML
MCP4441-103E/ML
MCP4441-104E/ML
MCP4441-502E/ML
MCP4441-503E/ML
MCP4441T-103E/ML
MCP4441T-104E/ML
MCP4441T-502E/ML
MCP4441T-503E/ML
MCP4451-103E/ML
MCP4451-104E/ML
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MCP4451T-502E/ML
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MCP4461-103E/ML
MCP4461-104E/ML
MCP4461-502E/ML
MCP4461-503E/ML
MCP4461T-103E/ML
MCP4461T-104E/ML
MCP4461T-502E/ML
MCP4461T-503E/ML
MCP73871-1AAI/ML
MCP73871-1CAI/ML
MCP73871-1CCI/ML
MCP73871-2AAI/ML
MCP73871-2CAI/ML
MCP73871-2CCI/ML
MCP73871-3CAI/ML
MCP73871-3CCI/ML
MCP73871-4CAI/ML
MCP73871-4CCI/ML
MCP73871T-1AAI/ML
MCP73871T-1CAI/ML
MCP73871T-1CCI/ML
MCP73871T-2AAI/ML

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Affected Catalog Part Numbers (CPN)

PCN_KSRA-10KDPB147
CATALOG_PART_NBR
MCP73871T-2CAI/ML
MCP73871T-2CCI/ML
MCP73871T-3CAI/ML
MCP73871T-3CCI/ML
MCP73871T-4CAI/ML
MCP73871T-4CCI/ML
PIC16F527-E/ML
PIC16F527-I/ML
PIC16F527T-I/ML
PIC16F631-E/ML
PIC16F631-I/ML
PIC16F631T-I/ML
PIC16F677-E/ML
PIC16F677-I/ML
PIC16F677T-I/ML
PIC16F677T-I/ML035
PIC16F677T-I/ML037
PIC16F685-E/ML
PIC16F685-I/ML
PIC16F685T-E/ML
PIC16F685T-I/ML
PIC16F687-E/ML
PIC16F687-E/ML034
PIC16F687-I/ML
PIC16F687T-E/ML
PIC16F687T-I/ML
PIC16F689-E/ML
PIC16F689-I/ML
PIC16F689T-E/ML
PIC16F689T-I/ML
PIC16F690-E/ML
PIC16F690-I/ML
PIC16F690T-E/ML
PIC16F690T-I/ML
PIC16F690T-I/ML050
PIC16F690T-I/MLC12
PIC16F785-E/ML
PIC16F785-I/ML
PIC16F785-I/MLC15
PIC16F785T-E/ML
PIC16F785T-I/ML
PIC16F785T-I/ML036
PIC16F785T-I/ML045

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Affected Catalog Part Numbers (CPN)

PCN_KSRA-10KDPB147
CATALOG_PART_NBR
PIC16F785T-I/ML047
PIC16F785T-I/MLC15
PIC16HV785-E/ML
PIC16HV785-I/ML
PIC16HV785T-E/ML
PIC16HV785T-I/ML